

Application No. 09/944,330
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AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

Claims 1-11 (canceled).

Claim 12 (currently amended): A method of manufacturing a hard disc comprising consisting essentially of the steps of.

providing a disc-shaped substrate having a first side and a second side, the substrate being sized and configured for use as a computer hard drive;

applying a polymer layer consisting of an optical quality polymer directly to at least one of the sides of the substrate to produce a polymer coated substrate; and

compression molding the polymer coated substrate, thereby fixing said polymer layer to said substrate.

Claim 13 (currently amended): The method as claimed in claim ~~44~~ 12 wherein the substrate is made from aluminum or an aluminum alloy.

Claim 14 (currently amended): The method as claimed in claim ~~44~~ 12 wherein the optical quality polymer is selected from the group consisting of an imide, an amide, a polycarbonate and combinations thereof.

Claim 15 (currently amended): The method as claimed in claim ~~44~~ 12 wherein said compression molding step is performed at a temperature of about 150° to 400°C at a pressure of about 1000 to 2000 psi.

Claim 16 (new): The method as claimed in claim 13 wherein said aluminum alloy is selected from the group consisting of 1xxx, 2xxx, 5xxx, 6xxx, and 8xxx series aluminum alloys.

Claim 17 (new): The method as claimed in claim 16 wherein said aluminum alloy is selected from the group consisting of 1050, 3003, 5005, and 6013 aluminum alloys.

Claim 18 (new): The method as claimed in claim 16 wherein said aluminum alloy is selected from the group consisting of 1000 and 5000 series alloys.

Claim 19 (new): The method as claimed in claim 12 wherein said substrate is about 0.2 to 1.0 mm thick.

Claim 20 (new): The method as claimed in claim 12 wherein said substrate is about 0.4 to 0.6 mm thick.

Claim 21 (new): The method as claimed in claim 12 wherein said polymer layer is formed from a polycarbonate polymer.

Claim 22 (new): The method as claimed in claim 12 wherein the thickness of the polymer layer on said first side of said substrate is 0.01 to 0.5 mm.

Claim 23 (new): The method as claimed in claim 12 wherein the thickness of the polymer layer on said second side of said substrate is 0.01 to 0.5 mm.